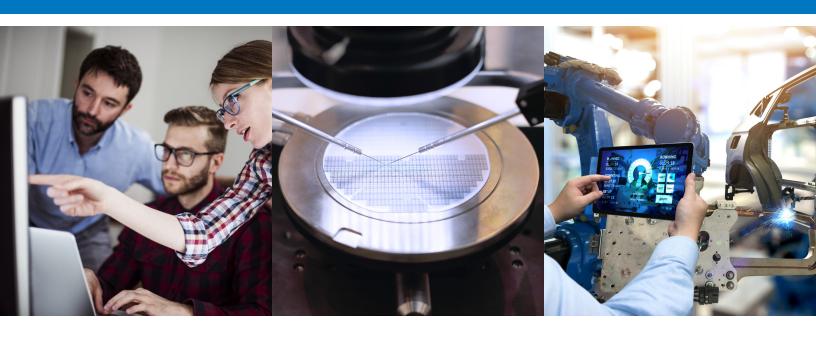
Leading-Edge Analog Mixed-Signal ASICs





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Microsemi offers custom integrated circuit designs of analog mixed-signal solutions for leading aerospace, avionics, defense, industrial, and automotive companies, and is a leading application-specific integrated circuit (ASIC) manufacturer of analog embedded systems. Our custom solutions include IC chips requiring high voltages, radiation tolerance, a focus on safety standards, and tolerance to harsh environments. Our fabless model ensures maximum flexibility in process selections, allowing for optimized designs and cost-effective solutions. Our experienced teams are dedicated to our customers' success by working in collaboration with them throughout all stages of design and production.

Reliable, Proven Application-Specific Integrated Circuit Development and Manufacturing

- Fully custom ASIC design flow
- Full supply services, from specification to production
- Custom specific standard product (CSSP)
- System integration and packaging optimization

Benefits to Customers

- IP investment protection
- Board space optimization
- Power optimization
- Overall application cost reduction
- Reliability improvement
- Obsolescence management
- Product differentiation from standard products

Experienced Team

- System architects
- Analog, digital, firmware, layout, packaging, test and product engineers
- Program managers

Safety, Quality, and Reliability

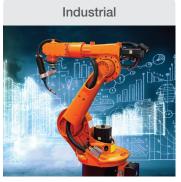
- Safety-critical applications: Automotive ISO 26262, Avionics DO-254
- Radiation tolerance: TID, SEL/SEU, ELDRS, prompt dose, neutron
- High-reliability, stringent-temperature:
 -55 °C to 225 °C
- Standards/certifications/classifications: AS9100, ISO 9001, MIL-PRF-38535, QML-V, QML-Q, ITAR, EAR

Packaging Solutions

- Flip Chip Multi-Layer Stack Up
- Bump Die and WLCSP
- Plastic Encapsulated
- Multi Chip Module (MCM)
- Hermetic High Reliability









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| Process | 1 μm DI 0.6 μm BiCMOS Rad-tolerant | 1 μm SOI Extreme Temp. | 0.35 μm HVCMOS AEC-Q100, Grade 0 | 180nm HVCMOS AECQ100, Grade 0 | 130nm BCD AECQ100, Grade 0 | 55/65nm (on roadmap) |
|---------------------------------------|--|---------------------------|--|-------------------------------------|---------------------------------------|----------------------------------|
| Max. Voltage | 200 V | 90 V | 45 V | 40 V | 85 V | 12 V |
| Temperature Range | –55 °C to 125 °C | –55 °C to 225 °C | -40 °C to 175 °C | –40 °C to 175 °C | -40 °C to 150 °C | -40 °C to 125 °C |
| Gate Density Gates/mm ² | 2.5K | 2.5K | 28K | 125K | 220K | 1M |
| Metal Layers | 3 | 3 | 4 | 6 | 8 | 8 |
| Memory Type | ROM, RAM, DPRAM, OTP | ROM, RAM, DPRAM, OTP | ROM, RAM, DPRAM, OTP, EEPROM | ROM, RAM, DPRAM, OTP, NVRAM | ROM, RAM, SRAM, OTP, MTP, FLASH | ROM, RAM, SRAM, OTP, FLASH |

Existing/Available IP

| Signal Conditioning and Converters | PGA, AFE, demodulators, peak detectors ADCs SAR, Sigma-Delta HV analog muxes, analog filters | |
|---|--|--|
| Digital Integration and Signal Processing | Digital filters Compiled memories Processors: 32-bit RISC and peripherals DSP functions | |
| Interfaces and Protections | SPI, I2C, JTAG, SENT, PWM, PSI5 ESD protection cells up to 4kV Reverse battery protections | |
| Drivers and Actuation | High-voltage drivers Line protectors and current limiters Motor drivers and pre-drivers | |
| Power Management | Switching regulators, linear regulators E-Fuse protection devices Charge pumps, thermal protection | |
| Clock Management | RC, VCO oscillators, PLLs LC tank exciter, sleep-mode timer | |



To stay up to date about Microsemi's ASIC solution products, email sales.support@microsemi.com or visit our Design Services Website: https://www.microsemi.com/product-directory/services/
1043-mixed-signal-asic-design-services

Microsemi is continually adding new products to its industry-leading portfolio.

For the most recent updates to our product line and for detailed information and specifications, please call, email, or visit our website.

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